

METHOD FOR MAKING MICROPOROUS SILICONE RESINS
WITH NARROW PORE-SIZE DISTRIBUTIONS

ABSTRACT

A method for preparing a microporous silicone resin which can be used to form low dielectric constant films useful for electrical insulating coatings on electronic devices comprising (A) contacting a hydridosilicon containing resin with an alkenyltriarylsilane in the presence of a platinum group metal-containing hydrosilation catalyst effecting formation of a silicon resin where at least 5 percent of silicon atoms are substituted with at least one triarylsilylalkylene group and 45 percent of silicon atoms are substituted with at least one hydrogen atom and (B) heating the silicon resin of step (A) in an inert atmosphere at a temperature sufficient to effect thermolysis of the triarylsilylalkylene groups from the silicon atoms.